



Material Content Data Sheet



Sales Product Name		SPB12N50C3		Issued		20. July 2018		
MA#		MA000737490						
Package		PG-TO263-3-2		Weight*		1560.61 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.017	0.45	0.45	4497	4497
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		59	
	non noble metal	iron	7439-89-6	0.304	0.02		195	
	non noble metal	copper	7440-50-8	304.026	19.48	19.51	194813	195067
	non noble metal	aluminium	7429-90-5	1.364	0.09	0.09	874	874
wire	non noble metal	aluminium	7429-90-5	1.364	0.09	0.09	874	874
encapsulation	organic material	carbon black	1333-86-4	10.267	0.66		6579	
	plastics	epoxy resin	-	112.939	7.24		72369	
	inorganic material	silicondioxide	60676-86-0	561.274	35.95	43.85	359650	438598
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6188	6188
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	146	147
solder	non noble metal	tin	7440-31-5	0.101	0.01		65	
	noble metal	silver	7440-22-4	0.126	0.01		81	
	non noble metal	lead	7439-92-1	4.831	0.31	0.33	3096	3242
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	iron	7439-89-6	0.548	0.04		351	
	non noble metal	copper	7440-50-8	547.666	35.09	35.14	350931	351387
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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